

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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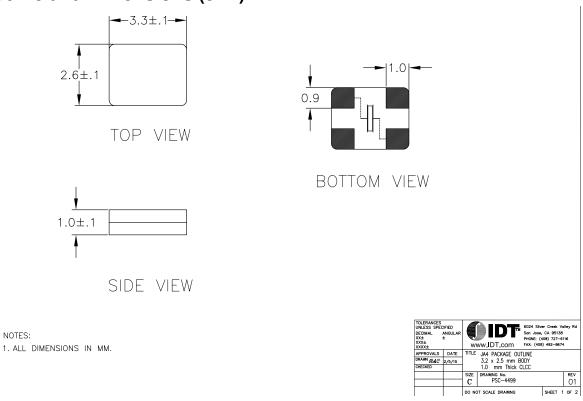


DATASHEET

Specifications

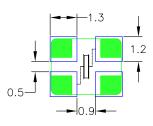
Parameters	Ratings/Units		
Frequency	25.000 MHz		
Resonance Mode	Fundamental		
Frequency Tolerance @ 25°C	±20 PPM Max		
Frequency Stability, ref @ 25°C Over Operating Temperature Range	±20 PPM Max		
Temperature Range, Operating (TOPR)	-40°C ~ +85°C		
Temperature Range, Storage (TsTG)	-40°C ~ +85°C		
Equivalent Series Resistance (ESR)	50 Ohms Max		
Shunt Capacitance (Co)	5 pF Max		
Load Capacitance (CL)	12 pF		
Drive Level	0.1 mW Max		
Aging over 10 years	±5 PPM Max		
Maximum Soldering Temp / Time	260°C / 10 Seconds		
Moisture Sensitivity Level (MSL)	1		
Termination Finish:	Au		
Weight (TYP)	16.75 mg		
RoHS Compliant, Pb-free			

Package Outline and Dimensions (JA4)



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Package Outline and Dimensions (JA4), cont.



RECOMMENDED LAND PATTERN

NOTES:

- 1. ALL DIMENSION ARE IN mm. ANGLES IN DEGREES.

- 2. TOP DOWN VIEW. AS VIEWED ON PCB.
 3. COMPONENT OUTLINE SHOW FOR REFERENCE IN GREEN.
 4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
 5. LAND PATTERN RECOMMENDATION PER IPC—7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

TOLERANCES UNLESS SPE DECIMAL XX± XXX± XXXX±		w w	NW.IDT.com	San Jose, PHONE: (4	er Creek Vo CA 95138 08) 727-6) 492-8674	116
APPROVALS	DATE	TITLE	JA4 PACKAGE OU	TLINE		
DRAWN RAC	2/5/15	i	3.2 x 2.5 mm B	ODY		
CHECKED		1.0 mm Thick CLCC				
		SIZE	DRAWING No.			REV
		C	PSC-4499			01
		DO NO	OT SCALE DRAWING		SHEET 2	0F 2

Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature
603-25-173JA4I	Cut-Tape	3.2 x 2.5 x 1.0 mm JA4 CLCC	-40 to +85 °C
603-25-173JA4I8	Tape and Reel	3.2 x 2.5 x 1.0 mm JA4 CLCC	-40 to +85 °C



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